L Number	Hits	Search Text	DB	Time stamp
29	2	29/$.ccls. and solder with (reference referring) same detect$3 same (land pad) and print$3 near position and mounting	USPAT; EPO; JPO	2004/04/02 13:52
30	12	solder$3 with (reference referring) same detect$3 same (land pad) and print$3 near position same detect$3 and mounting	USPAT; EPO; JPO	2004/04/02 14:04
31	2	solder$3 with paste with (reference referring) and detect$3 same (land pad) same print$3 near position and mounting	USPAT; EPO; JPO	2004/04/02 14:11
32	5	solder$3 with paste with (reference referring) and detect$3 same position and mounting same (land pad) same printing	USPAT; EPO; JPO	2004/04/02 14:22
33	6	solder$3 with paste with (reference referring) and detect$3 same position and mounting with component and (land pad) same printing	USPAT; EPO; JPO	2004/04/02 14:23
34	8	solder$3 with paste with (reference referring) and detect$3 same position and mounting and (land pad) and printing	USPAT; EPO; JPO	2004/04/02 14:24
35	11	solder$3 with paste with (reference referring) and detect$3 same position and mounting and printing	USPAT; EPO; JPO	2004/04/02 14:35
36	1	solder$3 with paste with (reference referring) and detect$3 same position and self$1alignment	USPAT; EPO; JPO	2004/04/02 14:35
37	2	solder$3 with paste with (reference referring) and detect$3 and position and self$1alignment	USPAT; EPO; JPO	2004/04/02 14:36
38	1	solder$3 with paste with (reference referring mark marking) same detect$3 and position and self$1alignment	USPAT; EPO; JPO	2004/04/02 14:36
39	1	solder$3 with paste with (reference referring mark marking) same detect$3 and (mark$3 position location) and self$1alignment	USPAT; EPO; JPO	2004/04/02 14:37
40	2	solder$3 with paste with (reference referring mark marking) and detect$3 and (mark$3 position location) and self$1alignment	USPAT; EPO; JPO	2004/04/02 14:47
41	2	solder$3 with paste with detect$3 and (mark$3 position location) and self$1alignment	USPAT; EPO; JPO	2004/04/02 14:49
42	23	solder$3 with paste with detect$3 and (mark$3 position location) and printing and mounting	USPAT; EPO; JPO	2004/04/02 15:14
43	18	solder$3 with paste with detect$3 and (decid$3 set$4 calculat$3) and printing and mounting	USPAT; EPO; JPO	2004/04/02 18:09
59	1	382/$.ccls. and solder$3 with paste with detect$3 and printing and mounting	USPAT; EPO; JPO	2004/04/02 18:10
60	1	73/$.ccls. and solder$3 with paste with detect$3 and printing and mounting	USPAT; EPO; JPO	2004/04/02 18:11
61	4	228/$.ccls. and solder$3 with paste with detect$3 and printing and mounting	USPAT; EPO; JPO	2004/04/02 18:11
-	4	mounting with component.ti. and nobuyasu.in.	USPAT; US-PGPUB; EPO; JPO	2004/04/01 11:42
-	14	detecting with mounting and solder adj paste and mounting with component and refer$4 with position	USPAT; EPO; JPO	2004/03/31 18:26
-	3	mounting with component and detecting with printing with position and solder adj paste same (land pad) and (referring reference)	USPAT; EPO; JPO	2004/04/01 15:00
-	5	mounting with component and detecting with printing with position and (controler controlling) and feed with forward and (referring reference)	USPAT; EPO; JPO	2004/04/01 15:02

-	0	mounting with component and detecting with printing and position with solder and (controler controlling) and feed with forward and (referring reference)	USPAT; EPO; JPO	2004/04/01 15:02
-	0	mounting with component and detecting with printing and position with solder$3 and (controler controlling) and feed with forward and (referring reference)	USPAT; EPO; JPO	2004/04/01 15:03
-	4	mounting with component and detecting with printing and position with (land pad) and (controler controlling) and feed with forward and (referring reference)	USPAT; EPO; JPO	2004/04/01 15:04
-	0	mounting with component and detecting with printing and position with (land pad) and control$4 and feed with forward and (referring reference) same solder$4	USPAT; EPO; JPO	2004/04/01 15:05
-	4	mounting with component and detecting with printing and position with (land pad) and control$4 and (referring reference) same solder$4	USPAT; EPO; JPO	2004/04/01 15:07
-	1	29/$.ccls. and mounting with component and detecting same printing and position with (land pad) and control$4 and (referring reference) same solder$4	USPAT; EPO; JPO	2004/04/01 15:10
-	13386	29/$.ccls. and mounting with component and detecting same printing same position and control$4 and (referring reference) same solder$4 feed near2 forward	USPAT; EPO; JPO	2004/04/01 15:11
-	0	29/$.ccls. and mounting with component and detecting same printing same position and control$4 and (referring reference) same solder$4 and feed near2 forward	USPAT; EPO; JPO	2004/04/01 15:12
-	0	mounting with component and detecting same printing same position and control$4 and (referring reference) same solder$4 and feed$3 near2 forward	USPAT; EPO; JPO	2004/04/01 15:13
-	0	mounting with component and detecting same printing same (mark position) and control$4 and (referring reference) same solder$4 and feed$3 near2 forward	USPAT; EPO; JPO	2004/04/01 15:13
-	0	mounting with component and detecting same printing and control$4 and (referring reference) same solder$4 same (mark position) and feed$3 near2 forward	USPAT; EPO; JPO	2004/04/01 15:14
-	0	mounting with component and detecting same printing and control$4 and (referring reference) same solder$4 and feed$3 near2 forward	USPAT; EPO; JPO	2004/04/01 15:14
-	8	mounting with component and detecting same printing and control$4 and (referring reference) same solder$4 same (mark position)	USPAT; EPO; JPO	2004/04/01 15:15